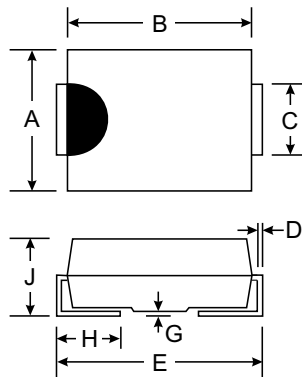


Features

- Glass Passivated Die Construction
- Super-Fast Recovery Time For High Efficiency
- Low Forward Voltage Drop and High Current Capability
- Surge Overload Rating to 100A Peak
- Ideally Suited for Automated Assembly
- Plastic Material: UL Flammability Classification Rating 94V-0

Mechanical Data

- Case: Molded Plastic
- Terminals: Solder Plated Terminal - Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- SMB Weight: 0.093 grams (approx.)
- SMC Weight: 0.21 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



	SMB		SMC	
Dim	Min	Max	Min	Max
A	3.30	3.94	5.59	6.22
B	4.06	4.57	6.60	7.11
C	1.96	2.21	2.75	3.18
D	0.15	0.31	0.15	0.31
E	5.00	5.59	7.75	8.13
G	0.10	0.20	0.10	0.20
H	0.76	1.52	0.76	1.52
J	2.00	2.62	2.00	2.62
All Dimensions in mm				

AB, BB, CB, DB Suffix Designates SMB Package
 A, B, C, D, Suffix Designates SMC Package

Maximum Ratings and Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	ES3A/B	ES3B/B	ES3C/B	ES3D/B	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	50	100	150	200	V
Working Peak Reverse Voltage	V_{RWM}					
DC Blocking Voltage	V_R					
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	105	140	V
Average Rectified Output Current @ $T_T = 100^\circ\text{C}$	I_O	3.0				A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	100				A
Forward Voltage @ $I_F = 3.0\text{A}$	V_{FM}	0.9				V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A = 125^\circ\text{C}$	I_{RM}	10 500				μA
Reverse Recovery Time (Note 3)	t_{rr}	25				ns
Typical Junction Capacitance (Note 2)	C_j	45				pF
Typical Thermal Resistance, Junction to Terminal (Note 1)	$R_{\theta JT}$	15				K/W
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150				$^\circ\text{C}$

- Notes:
1. Unit mounted on PC board with 5.0 mm^2 (0.013 mm thick) copper pads as heat sink.
 2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
 3. Measured with $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $t_{rr} = 0.25\text{A}$. See Figure 5.

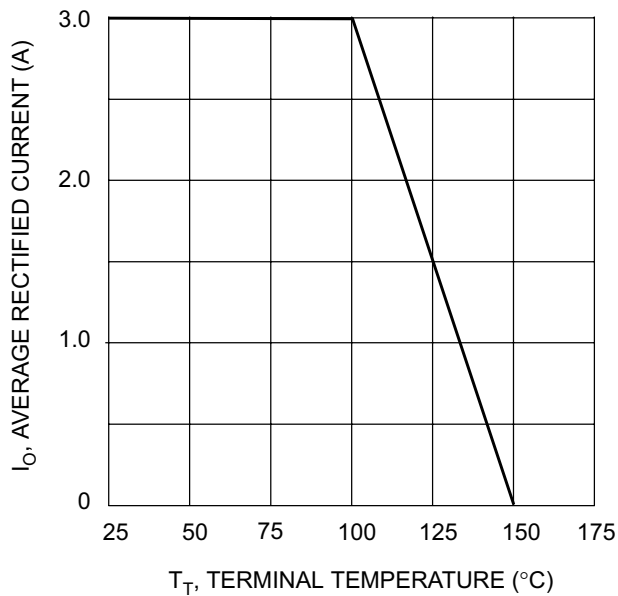


Fig. 1 Forward Current Derating Curve

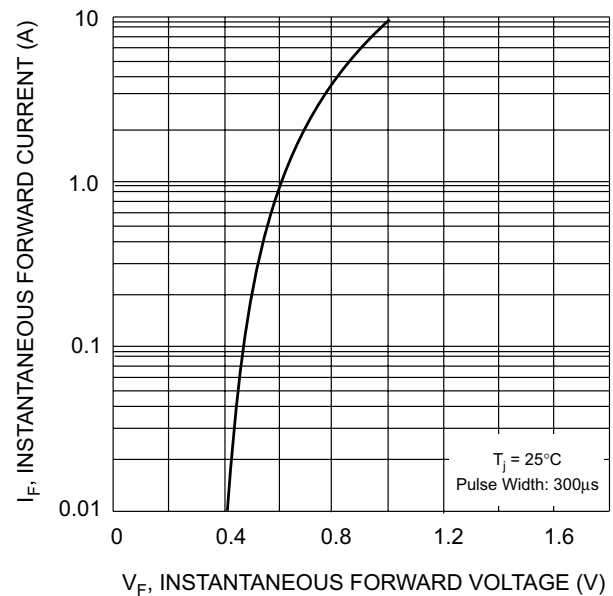


Fig. 2 Typical Forward Characteristics

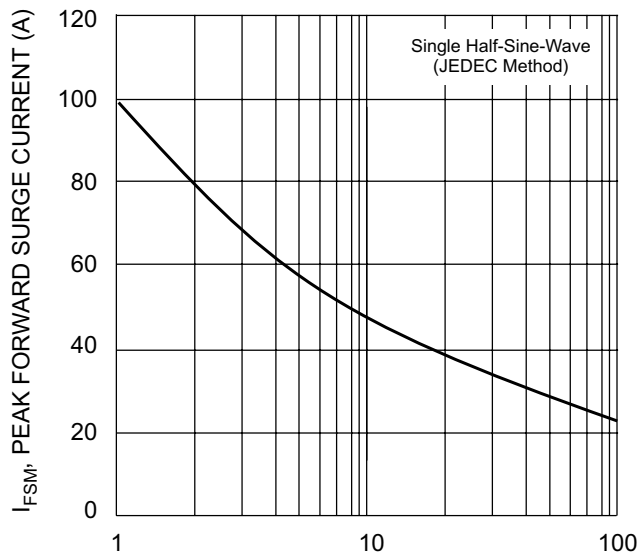


Fig. 3 Surge Current Derating Curve

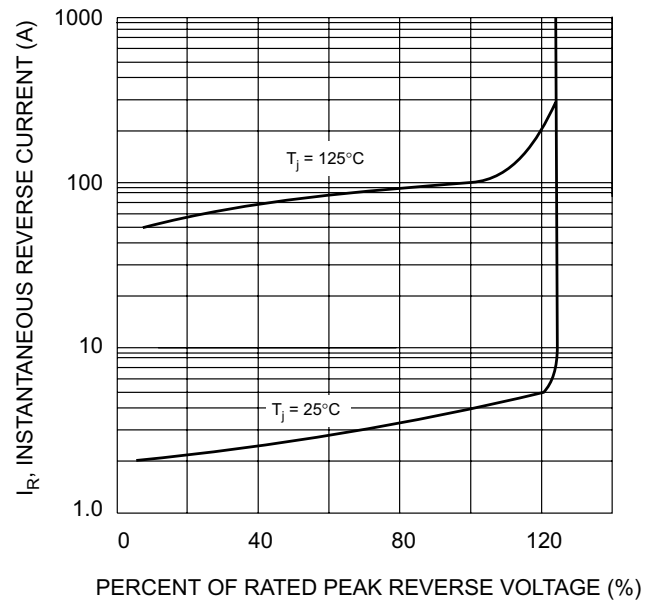
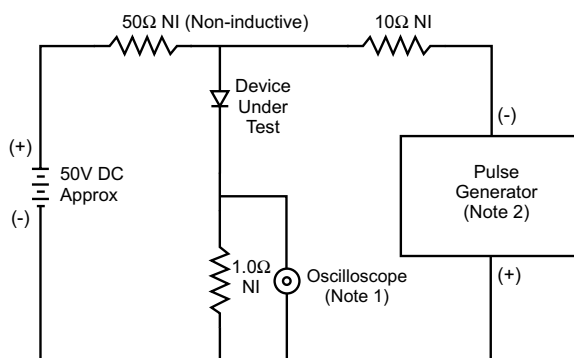


Fig. 4 Typical Reverse Characteristics



- Notes:
1. Rise Time = 7.0ns max. Input Impedance = 1.0M Ω , 22pF.
 2. Rise Time = 10ns max. Input Impedance = 50 Ω .

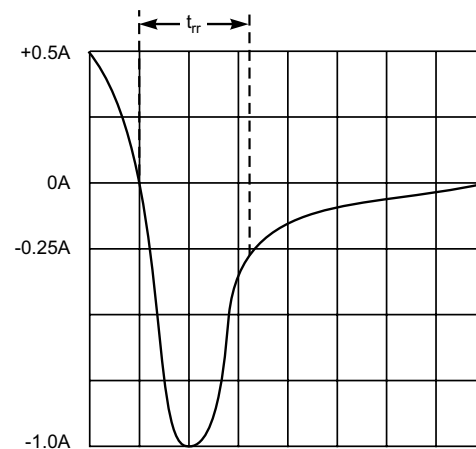


Fig. 5 Reverse Recovery Time Characteristic and Test Circuit